

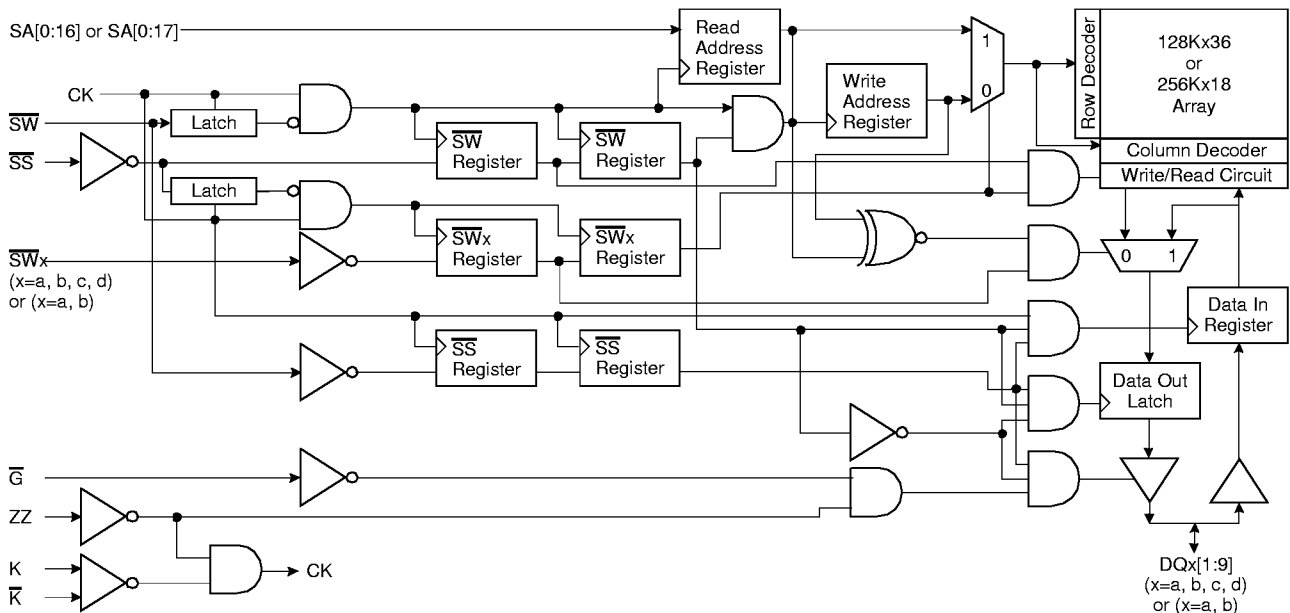
128Kx36 & 256Kx18 Synchronous Pipelined SRAM

FEATURES

- 128Kx36 or 256Kx18 Organizations.
- 3.3V Core/2.5V Output Power Supply.
- LVC MOS Input and Output Levels.
- Differential, PECL Clock Inputs K, \bar{K} .
- Synchronous Read and Write Operation
- Registered Input and Latched Output
- Internal Pipeline Latches to Support Late Write.
- Byte Write Capability(four byte write selects, one for each 9 bits)
- Synchronous or Asynchronous Output Enable.
- Power Down Mode via ZZ Signal.
- JTAG 1149.1 Compatible Test Access port.
- 119(7x17) Pin Ball Grid Array Package(14mm x 22mm).

Organization	Part Number	Cycle Time	Access Time
128Kx36	KM736FV4002H-8	8	7.0
	KM736FV4002H-9	9	8.0
	KM736FV4002H-10	10	9.0
256Kx18	KM718FV4002H-8	8	7.0
	KM718FV4002H-9	9	8.0
	KM718FV4002H-10	10	9.0

FUNCTIONAL BLOCK DIAGRAM



PIN DESCRIPTION

Pin Name	Pin Description	Pin Name	Pin Description
K, \bar{K}	Differential Clocks(PECL Level)	C, \bar{C}	Differential Output Clocks
SAn	Synchronous Address Input	M1, M2	Read Protocol Mode Pins
DQn	Bi-directional Data Bus	\bar{G}	Asynchronous Output Enable
\bar{SW}	Synchronous Global Write Enable	\bar{SS}	Synchronous Select
\bar{SW}_a	Synchronous Byte a Write Enable	TCK	JTAG Test Clock
\bar{SW}_b	Synchronous Byte b Write Enable	TMS	JTAG Test Mode Select
\bar{SW}_c	Synchronous Byte c Write Enable	TDI	JTAG Test Data Input
\bar{SW}_d	Synchronous Byte d Write Enable	TDO	JTAG Test Data Output
ZZ	Asynchronous Power Down	ZQ	Output Driver Impedance Control Input HSTL Level
VDD	Core Power Supply	Vss	GND
VDDQ	Output Power Supply	NC	No Connection
VREF	HSTL Input Reference Voltage		

NOTE : 1. This SRAM only supports single clock, register-latch read protocol and have fixed impedance output driver. Therefore the following inputs must be set with power up and must not change during SRAM operation ; C=VDD, \bar{C} =VSS, M1=VDD, M2=VSS, ZQ=VDD and VREF=VDD. But they are also designed to operate being left floating.

PACKAGE PIN CONFIGURATIONS(TOP VIEW)

KM736FV4002(128Kx36)

	1	2	3	4	5	6	7
A	VDDQ	SA13	SA10	NC	SA7	SA4	VDDQ
B	NC	NC	SA9	NC	SA8	NC	NC
C	NC	SA12	SA11	VDD	SA6	SA5	NC
D	DQc8	DQc9	VSS	ZQ	VSS	DQb9	DQb8
E	DQc6	DQc7	VSS	\overline{SS}	VSS	DQb7	DQb6
F	VDDQ	DQc5	VSS	\overline{G}	VSS	DQb5	VDDQ
G	DQc3	DQc4	\overline{SWc}	\overline{C}	\overline{SWb}	DQb4	DQb3
H	DQc1	DQc2	VSS	C	VSS	DQb2	DQb1
J	VDDQ	VDD	VREF	VDD	VREF	VDD	VDDQ
K	DQd1	DQd2	VSS	K	VSS	DQa2	DQa1
L	DQd3	DQd4	\overline{SWd}	\overline{K}	\overline{SWa}	DQa4	DQa3
M	VDDQ	DQd5	VSS	\overline{SW}	VSS	DQa5	VDDQ
N	DQd6	DQd7	VSS	SA16	VSS	DQa7	DQa6
P	DQd8	DQd9	VSS	SA0	VSS	DQa9	DQa8
R	NC	SA15	M1	VDD	M2	SA2	NC
T	NC	NC	SA14	SA1	SA3	NC	ZZ
U	VDDQ	TMS	TDI	TCK	TDO	NC	VDDQ

KM718FV4002(256Kx18)

	1	2	3	4	5	6	7
A	VDDQ	SA13	SA10	NC	SA7	SA4	VDDQ
B	NC	NC	SA9	NC	SA8	NC	NC
C	NC	SA12	SA11	VDD	SA6	SA5	NC
D	DQb1	NC	VSS	ZQ	VSS	DQa9	NC
E	NC	DQb2	VSS	\overline{SS}	VSS	NC	DQa8
F	VDDQ	NC	VSS	\overline{G}	VSS	DQa7	VDDQ
G	NC	DQb3	\overline{SWb}	\overline{C}	VSS	NC	DQa6
H	DQb4	NC	VSS	C	VSS	DQa5	NC
J	VDDQ	VDD	VREF	VDD	VREF	VDD	VDDQ
K	NC	DQb5	VSS	K	VSS	NC	DQa4
L	DQb6	NC	VSS	\overline{K}	\overline{SWa}	DQa3	NC
M	VDDQ	DQb7	VSS	\overline{SW}	VSS	NC	VDDQ
N	DQb8	NC	VSS	SA16	VSS	DQa2	NC
P	NC	DQb9	VSS	SA1	VSS	NC	DQa1
R	NC	SA15	M1	VDD	M2	SA2	NC
T	NC	SA17	SA14	NC	SA3	SA0	ZZ
U	VDDQ	TMS	TDI	TCK	TDO	NC	VDDQ

FUNCTION DESCRIPTION

The KM736FV4002 and KM718FV4002 are 4,718,592 bit Synchronous SRAM. It is organized as 131,072 words of 36 bits(or 262, 144 words of 18 bits) and is implemented in SAMSUNG's advanced CMOS technology.

Single differential PECL level K clocks are used to initiate the read/write operation and all internal operations are self-timed. At the rising edge of K clock, all addresses, Write Enables, Synchronous Select and Data Ins are registered internally. Data outputs are updated from output latches of the falling edge of the K clock. An internal write data buffer allows write data to follow one cycle after addresses and controls. The package is 119(7x17) Ball Grid Array with balls on a 1.27mm pitch.

Read Operation

During reads, the address is registered during the clock rising edge and the internal array is read. The data is driven to the CPU in the following cycle. \overline{SS} is driven low during this cycle, signaling that the SRAM should drive out the data.

During consecutive read cycles where the address is the same, the data output must be held constantly without any glitches. This characteristic is because the SRAM will be read by devices that will operate slower than the SRAM frequency and will require multiple SRAM cycles to perform a single read operation.

Write(Store) Operation

All addresses and \overline{SW} are both sampled on the clock rising edge. \overline{SW} is low on the rising clock. Write data is sampled on the rising clock, one cycle after write address and \overline{SW} have been sampled by the SRAM. \overline{SS} will be driven low during the same cycle that the Address, \overline{SW} and $\overline{SW}[a:d]$ are valid to signal that a valid operations is on the Address and Control Input.

Pipelined write are supported. This is done by using write data buffers on the SRAM that capture the write addresses on one write cycle, and write the array on the next write cycle. The "next write cycle" can actually be many cycles away, broken by a series of read cycles. Byte writes are supported. The byte write signals $\overline{SW}[a:d]$ signal which 9-bit bytes will be written. Timing of $\overline{SW}[a:d]$ is the same as the \overline{SW} signal.

Bypass Read Operation

Since write data is not fully written into the array on first write cycle, there is a need to sense the address in case a future read is to be done from the location that has not been written yet. For this case, the address comparator check to see if the new read address is the same as the contents of the stored write address Latch. If the contents match, the read data must be supplied from the stored write data latch with standard read timing. If there is no match, the read data comes from the SRAM array. The bypassing of the SRAM array occurs on a byte by byte basis. If one byte is written and the other bytes are not, read data from the last written will have new byte data from the write data buffer and the other bytes from the SRAM array.

Low Power Dissipation Mode

During normal operation, asynchronous signal ZZ must be pulled low. Low Power Mode is enabled by switching ZZ high. When the SRAM is in Power Down Mode, the outputs will go to a Hi-Z state and the SRAM will draw standby current. SRAM data will be preserved and a recovery time(tZZR) is required before the SRAM resumes to normal operation.

TRUTH TABLE

K	ZZ	\overline{G}	\overline{SS}	\overline{SW}	\overline{SWa}	\overline{SWb}	\overline{SWc}	\overline{SWd}	DQa	DQb	DQc	DQd	Operation
X	H	X	X	X	X	X	X	X	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Power Down Mode. No Operation
X	L	H	X	X	X	X	X	X	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Output Disabled. No Operation
\overline{jE}	L	L	H	X	X	X	X	X	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Output Disabled. No Operation
\overline{jE}	L	L	L	H	X	X	X	X	DOUT	DOUT	DOUT	DOUT	Read Cycle
\overline{jE}	L	L	L	L	H	H	H	H	Hi-Z	Hi-Z	Hi-Z	Hi-Z	No Bytes Written
\overline{jE}	L	L	L	L	L	H	H	H	DIN	Hi-Z	Hi-Z	Hi-Z	Write first byte
\overline{jE}	L	L	L	L	L	L	H	H	Hi-Z	DIN	Hi-Z	Hi-Z	Write second byte
\overline{jE}	L	L	L	L	L	H	H	L	Hi-Z	Hi-Z	DIN	Hi-Z	Write third byte
\overline{jE}	L	L	L	L	L	H	H	H	Hi-Z	Hi-Z	Hi-Z	DIN	Write fourth byte
\overline{jE}	L	L	L	L	L	L	L	L	DIN	DIN	DIN	DIN	Write all byte

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Core Supply Voltage Relative to Vss	VDD	-0.5 to 4.6	V
Output Supply Voltage Relative to Vss	VDDQ	-0.5 to 4.6	V
Voltage on any I/O pin Relative to Vss	VTERM	-0.5 to VDDQ+0.5	V
Maximum Power Dissipation	PD	2.5	W
Output Short-Circuit Current	IOUT	25	mA
Operating Temperature	TOPR	0 to 70	°C
Storage Temperature	TSTG	-55 to 125	°C

NOTE : Stresses greater than those listed under " Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS

Parameter	Symbol	Min	Typ	Max	Unit	Note
Core Power Supply Voltage	VDD	3.15	3.3	3.45	V	
Output Power Supply Voltage	VDDQ	2.4	2.5	2.6	V	
Input High Level	VIH	1.7	-	VDD + 0.3	V	1, 2
Input Low Level	VIL	-0.3	-	0.7	V	1, 3
PECL Clock Input High Level	VIH-PECL	2.135	-	2.420	V	1
PECL Clock Input Low Level	VIL-PECL	1.490	-	1.825	V	1
Operating Junction Temperature	TJ	10	-	110	°C	4

NOTE : 1. These are DC VIH/VIH spec. The AC VIH/VIL levels are defined separately for measuring timing parameters.
 2. VIH (Max)DC = VDD+0.3V, VIH (Max)AC = VDD+1.5V(pulse width ; 5ns).
 3. VIL (Min)DC = -0.3V, VIL (Min)AC = -1.5V(pulse width ; 5ns).
 4. Junction temperature is a function of on-chip power dissipation, package thermal impedance, mounting site temperature and mounting site thermal impedance. $T_J = T_A + P_D \times \theta_{JA}$

DC CHARACTERISTICS

Parameter	Symbol	Min	Max	Unit	Note
Average Power Supply Operating Current-x36 (VIN=VIH or VIL, ZZ & SS=VIL)	IDD	-	450	mA	1
Average Power Supply Operating Current-x18 (VIN=VIH or VIL, ZZ & SS=VIL)	IDD	-	400	mA	1
Power Supply Standby Current (VIN=VIH or VIL, ZZ =VIH)	ISB	-	100	mA	1
Input Leakage Current (VIN=Vss or VDD)	ILI	-1	1	µA	
Output Leakage Current (VOUT=Vss or VDD, ZZ =VIH)	ILO	-5	5	µA	
Output High Voltage(LOH=-2mA)	VOH	2.0	VDDQ	V	
Output Low Voltage(LOL=2mA)	VOL	Vss	0.4	V	

NOTE : 1. Minimum cycle. IOUT=0mA.

PIN CAPACITANCE

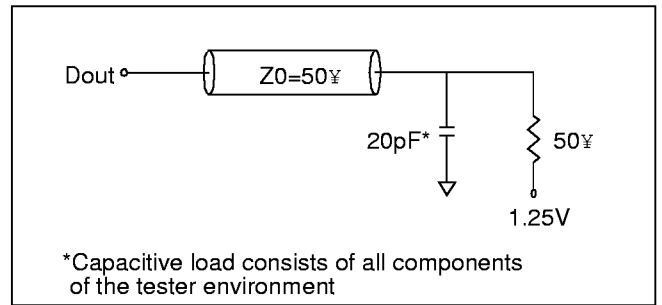
Parameter	Symbol	Pin Name	Min	Typ	Max	Unit
Input Capacitance	CIN	K, \bar{K} , \bar{SS} , \bar{SW} , \bar{G} , ZZ \bar{SW}_x , ZQ, M1, M2, SAn, TCK, TMS, TDI	3	4	5	pF
Output Capacitance	COUT	DQn, TDO	5	6	7	pF

NOTE : Periodically sampled and 100% tested.(dV=0V, f=1MHz)

AC TEST CONDITIONS

Parameter	Symbol	Value	Unit
Input High/Low Level	V _{IH} /V _{IL}	2.5/0.0	V
Clock Input High/Low Level(PECL)	V _{IH} /V _{IL}	2.4/1.5	V
Input Rise/Fall Time	T _R /T _F	1.0/1.0	ns
Clock Input Rise/Fall Time(PECL)	T _R /T _F	0.5/0.5	ns
Output Rise/Fall Time	T _R /T _F	0.5~1.0	ns
Input and Out Timing Reference Level		1.25	V
Clock Input Timing Reference Level		Cross Point	V

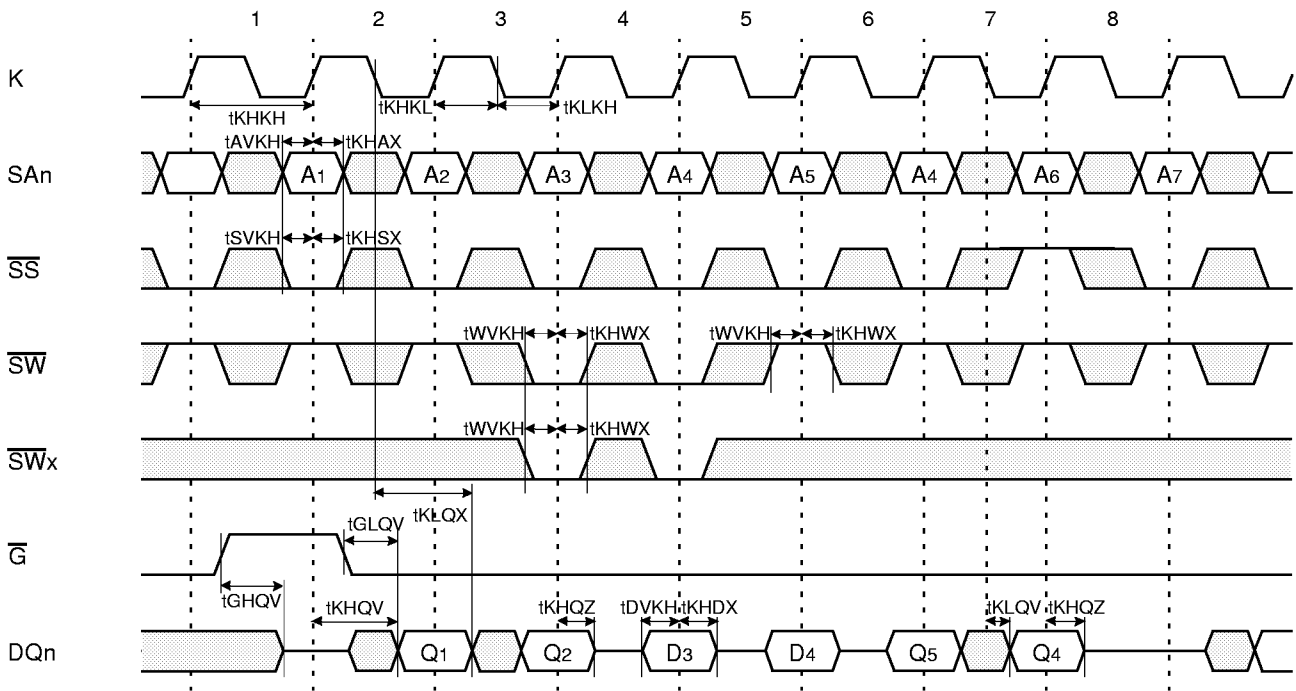
AC TEST OUTPUT LOAD



AC CHARACTERISTICS

Parameter	Symbol	-8		-9		-10		Unit	Note
		Min	Max	Min	Max	Min	Max		
Clock Cycle Time	tKHKH	8.0	-	9.0	-	10.0	-	ns	
Clock High Pulse Width	tKHKL	3.2	-	3.6	-	4.0	-	ns	
Clock Low Pulse Width	tKCLKH	3.2	-	3.6	-	4.0	-	ns	
Clock High to Output Valid	tKHQV	-	7.0	-	8.0	-	9.0	ns	
Clock Low to Output Valid	tKLQV	-	2.5	-	3.0	-	3.5	ns	
Clock Low to Output Hold	tKLQX	1.0	-	1.0	-	1.0	-	ns	
Address Setup Time	tAVKH	0.5	-	0.5	-	0.1	-	ns	
Address Hold Time	tKHAX	1.0	-	1.0	-	1.0	-	ns	
Write Data Setup Time	tDVKH	0.5	-	0.5	-	0.5	-	ns	
Write Data Hold Time	tKHDX	1.0	-	1.0	-	1.0	-	ns	
\bar{SW} , \bar{SW} [a:d] Setup Time	tWVKH	0.5	-	0.5	-	0.5	-	ns	
\bar{SW} , \bar{SW} [a:d] Hold Time	tKH WX	1.0	-	1.0	-	1.0	-	ns	
\bar{SS} Setup Time	tSVKH	0.5	-	0.5	-	0.5	-	ns	
\bar{SS} Hold Time	tKHSX	1.0	-	1.0	-	1.0	-	ns	
Clock High to Output Hi-Z	tKHQZ	-	2.5	-	3.0	-	3.5	ns	
Clock Low to Output Low-Z	tKHQX1	1.0	-	1.0	-	1.0	-	ns	
\bar{G} High to Output High-Z	tGHQZ	-	2.5	-	3.0	-	3.5	ns	
\bar{G} High to Output Low-Z	tGLQX	0.5	-	0.5	-	0.5	-	ns	
\bar{G} Low to Output Valid	tGLQV	-	2.5	-	3.0	-	3.5	ns	
ZZ High to Power Down(Sleep Time)	tZZE	-	8.0	-	9.0	-	10.0	ns	
ZZ Low to Recovery(Wake-up Time)	tZZR	-	8.0	-	9.0	-	10.0	ns	

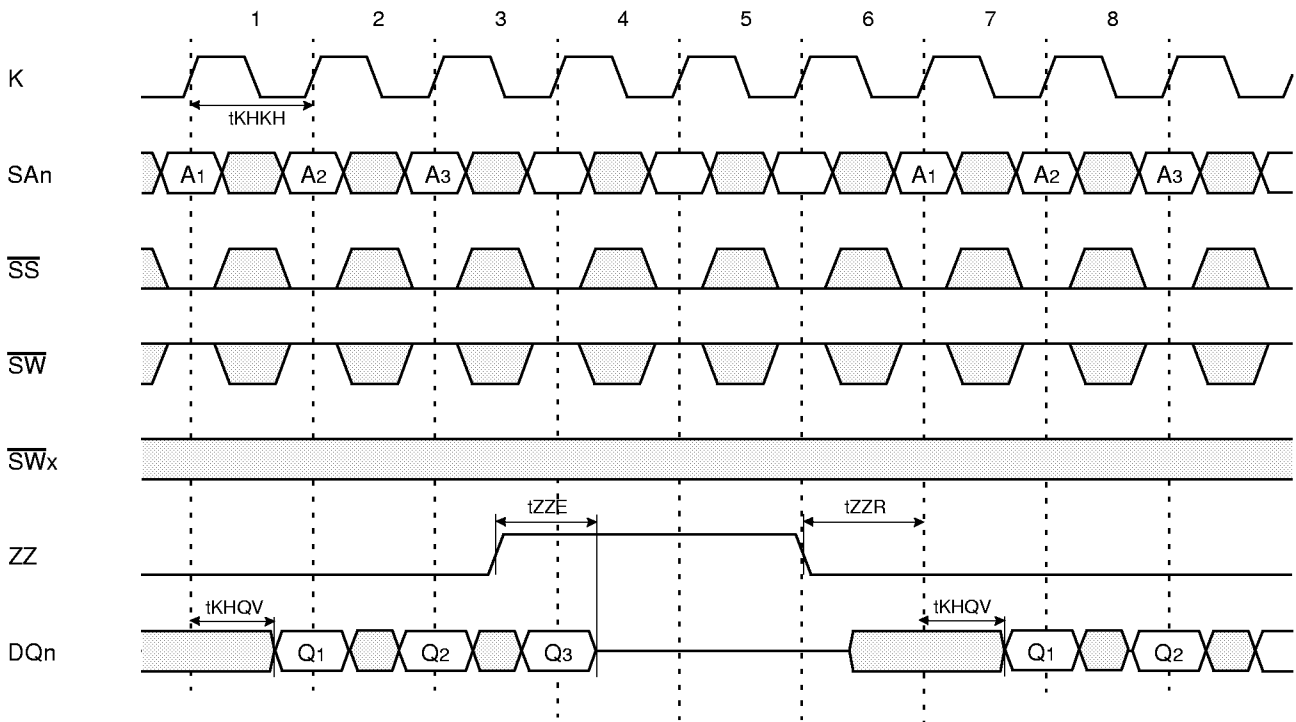
TIMING WAVEFORMS OF NORMAL ACTIVE CYCLES



NOTE :

1. D3 is the input data written in memory location A3.
2. Q4 is the output data read from the write data buffer(not from the cell array), as a result of address A4 being a match from the last write cycle address.
3. Data is valid at the output at the later of tKHQV following the rising clock edge, or tKLQV following the following clock edge.
4. When SS is sampled high or SW is sampled low on the rising edge of clock, the outputs go into Hi-Z state no later than tKHQZ following the rising clock edge.
5. When SS is low and SW is high on the rising edge of clock, the outputs go into Low-Z state(being driven) no earlier than tKHQX following the next falling edge of clock.
6. When the SRAM is deselected, the output goes Hi-Z at tKHQZ following the rising clock edge. On the next read cycle, note that the SRAM output do not leave the Hi-Z state until tKLQX after the falling clock edge.

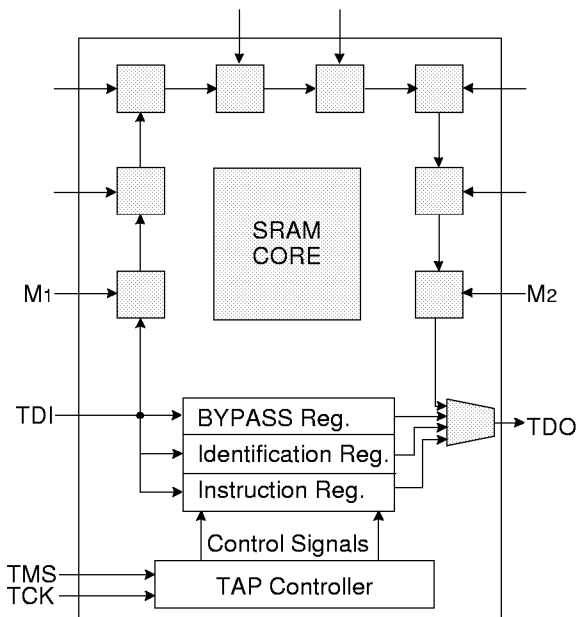
TIMING WAVEFORMS OF STANDBY CYCLES



IEEE 1149.1 TEST ACCESS PORT AND BOUNDARY SCAN-JTAG

This part contains an IEEE standard 1149.1 Compatible Test Access Port(TAP). The package pads are monitored by the Serial Scan circuitry when in test mode. This is to support connectivity testing during manufacturing and system diagnostics. Internal data is not driven out of the SRAM under JTAG control. In conformance with IEEE 1149.1, the SRAM contains a TAP controller, Instruction Register, Bypass Register and ID register. The TAP controller has a standard 16-state machine that resets internally upon power-up, therefore, TRST signal is not required. It is possible to use this device without utilizing the TAP. To disable the TAP controller without interfacing with normal operation of the SRAM, TCK must be tied to Vss to preclude mid level input. TMS and TDI are designed so an undriven input will produce a response identical to the application of a logic 1, and may be left unconnected. But they may also be tied to VDD through a resistor. TDO should be left unconnected.

JTAG Block Diagram



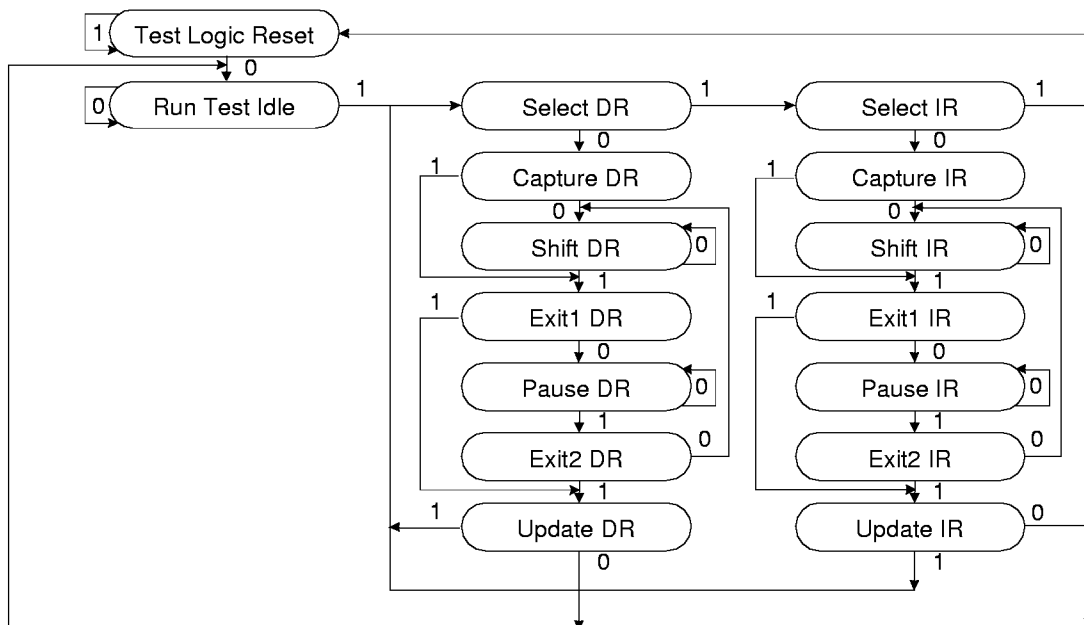
JTAG Instruction Coding

IR2	IR1	IR0	Instruction	TDO Output	Notes
0	0	0	SAMPLE-Z	Boundary Scan Register	1
0	0	1	IDCODE	Identification Register	2
0	1	0	SAMPLE-Z	Boundary Scan Register	1
0	1	1	BYPASS	Bypass Register	3
1	0	0	SAMPLE	Boundary Scan Register	4
1	0	1	BYPASS	Bypass Register	3
1	1	0	BYPASS	Bypass Register	3
1	1	1	BYPASS	Bypass Register	3

NOTE :

1. Places DQs in Hi-Z in order to sample all input data regardless of other SRAM inputs.
2. TDI is sampled as an input to the first ID register to allow for the serial shift of the external TDI data.
3. Bypass register is initiated to Vss when BYPASS instruction is invoked. The Bypass Register also holds serially loaded TDI when exiting the Shift DR states.
4. SAMPLE instruction dose not places DQs in Hi-Z.

TAP Controller State Diagram



SCAN REGISTER DEFINITION

Part	Instruction Register	Bypass Register	ID Register	Boundary Scan
128Kx36	3 bits	1 bits	32 bits	70 bits
256Kx18	3 bits	1 bits	32 bits	51 bits

ID REGISTER DEFINITION

Part	Revision Number (31:28)	Part Configuration (27:18)	Vendor Definition (17:12)	Samsung JEDEC Code (11: 1)	Start Bit(0)
128Kx36	0000	00101 00100	000000	00001001110	1
256Kx18	0000	00110 00011	000000	00001001110	1

BOUNDARY SCAN EXIT ORDER(x36)

36	3B	SA9		SA8	5B	35
37	2B	NC		NC	6B	34
38	3A	SA10		SA7	5A	33
39	3C	SA11		SA6	5C	32
40	2C	SA12		SA5	6C	31
41	2A	SA13		SA4	6A	30
42	2D	DQc9		DQb9	6D	29
43	1D	DQc8		DQb8	7D	28
44	2E	DQc7		DQb7	6E	27
45	1E	DQc6		DQb6	7E	26
46	2F	DQc5		DQb5	6F	25
47	2G	DQc4		DQb4	6G	24
48	1G	DQc3		DQb3	7G	23
49	2H	DQc2		DQb2	6H	22
50	1H	DQc1		DQb1	7H	21
51	3G	\overline{SWc}		\overline{SWb}	5G	20
52	4D	ZQ		\overline{G}	4F	19
53	4E	\overline{SS}		K	4K	18
54	4G	\overline{C}		\overline{K}	4L	17
55	4H	C		\overline{SWa}	5L	16
56	4M	\overline{SW}		DQa1	7K	15
57	3L	\overline{SWd}		DQa2	6K	14
58	1K	DQd1		DQa3	7L	13
59	2K	DQd2		DQa4	6L	12
60	1L	DQd3		DQa5	6M	11
61	2L	DQd4		DQa6	7N	10
62	2M	DQd5		DQa7	6N	9
63	1N	DQd6		DQa8	7P	8
64	2N	DQd7		DQa9	6P	7
65	1P	DQd8		ZZ	7T	6
66	2P	DQd9		SA3	5T	5
67	3T	SA14		SA2	6R	4
68	2R	SA15		SA1	4T	3
69	4N	SA16		SA0	4P	2
70	3R	M1		M2	5R	1

BOUNDARY SCAN EXIT ORDER(x18)

26	3B	SA9		SA8	5B	25
27	2B	NC		NC	6B	24
28	3A	SA10		SA7	5A	23
29	3C	SA11		SA6	5C	22
30	2C	SA12		SA5	6C	21
31	2A	SA13		SA4	6A	20
				DQa9	6D	19
32	1D	DQb1				
33	2E	DQb2				
				DQa8	7E	18
				DQa7	6F	17
34	2G	DQb3				
				DQa6	7G	16
				DQa5	6H	15
35	1H	DQb4				
36	3G	\overline{SWb}				
37	4D	ZQ		\overline{G}	4F	14
38	4E	\overline{SS}		K	4K	13
39	4G	\overline{C}		\overline{K}	4L	12
40	4H	C		\overline{SWa}	5L	11
41	4M	\overline{SW}		DQa4	7K	10
42	2K	DQb5		DQa3	6L	9
43	1L	DQb6				
44	2M	DQb7		DQa2	6N	8
45	1N	DQb8		DQa1	7P	7
				ZZ	7T	6
46	2P	DQb9		SA3	5T	5
47	3T	SA14		SA2	6R	4
48	2R	SA15				
49	4N	SA16		SA1	4P	3
50	2T	SA17		SA0	6T	2
51	3R	M1		M2	5R	1

NOTE : 1. Pins 6B and 2B are no connection pin to internal chip. These pins are place holders for 16M part and the scanned data are fixed to "0" for this 4M parts.

JTAG DC OPERATING CONDITIONS

Parameter	Symbol	Min	Typ	Max	Unit	Note
Power Supply Voltage	VDD	3.15	3.3	3.45	V	
Input High Level	V _{IH}	2.0	-	V _{DD} +0.3	V	
Input Low Level	V _{IL}	-0.3	-	0.8	V	
Output High Voltage(I _{OH} =-2mA)	V _{OH}	2.4	-	V _{DD}	V	
Output Low Voltage(I _{OL} =2mA)	V _{OL}	V _{SS}	-	0.4	V	

NOTE : 1. The input level of SRAM pin is to follow the SRAM DC specification.

JTAG AC TEST CONDITIONS

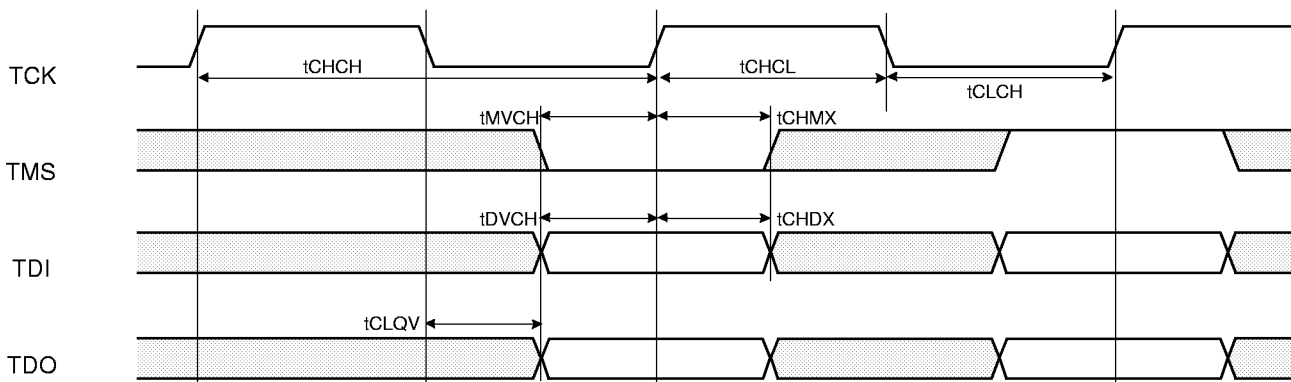
Parameter	Symbol	Min	Unit	Note
Input High/Low Level	V _{IH} /V _{IL}	3.0/0.0	V	
Input Rise/Fall Time	T _R /T _F	2.0/2.0	ns	
Input and Output Timing Reference Level		1.5	V	1

NOTE : 1. See SRAM AC test output load on page 5.

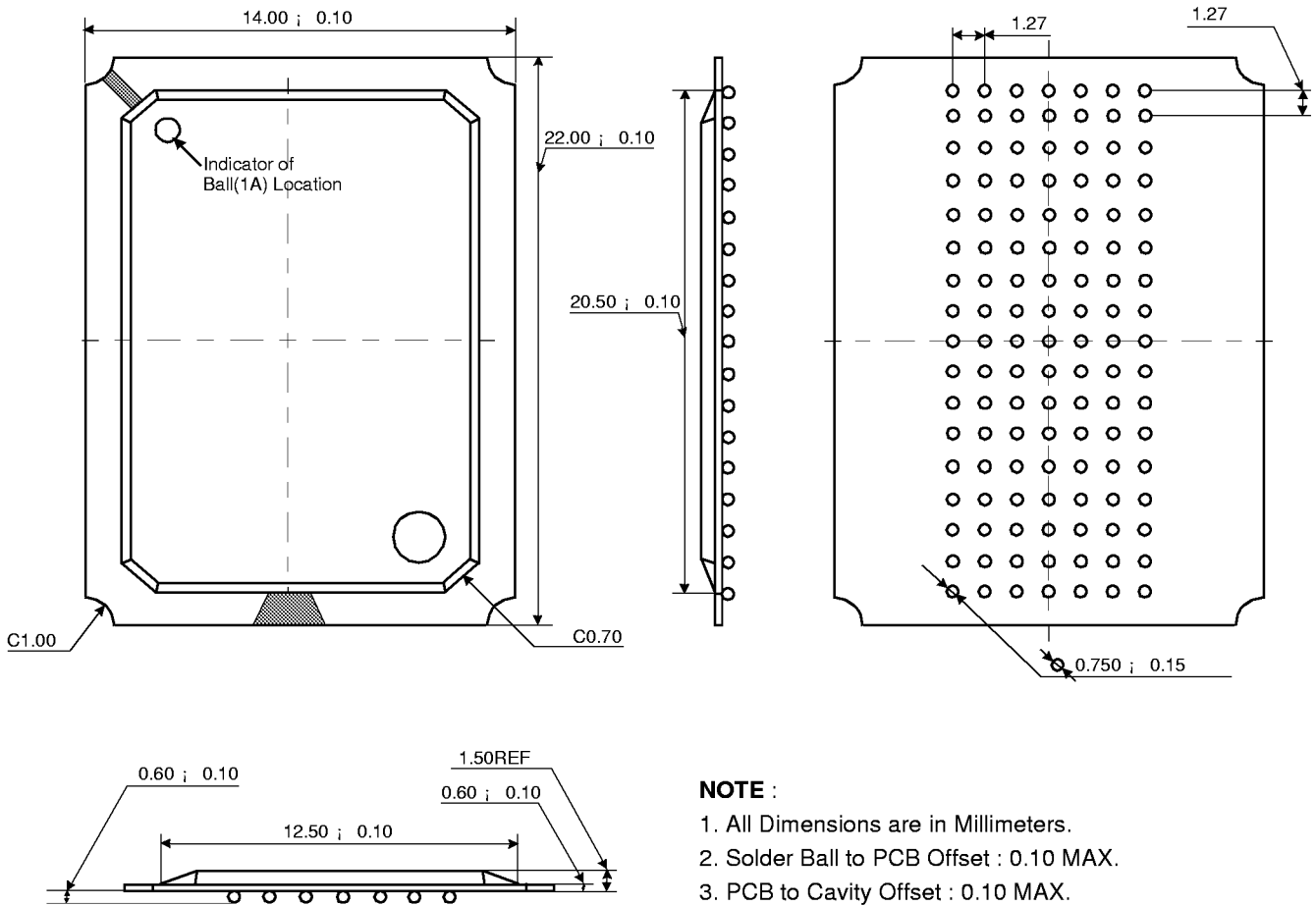
JTAG AC Characteristics

Parameter	Symbol	Min	Max	Unit	Note
TCK Cycle Time	t _{CHCH}	50	-	ns	
TCK High Pulse Width	t _{CHCL}	20	-	ns	
TCK Low Pulse Width	t _{CLCH}	20	-	ns	
TMS Input Setup Time	t _{MVCH}	5	-	ns	
TMS Input Hold Time	t _{CHMX}	5	-	ns	
TDI Input Setup Time	t _{DVCH}	5	-	ns	
TDI Input Hold Time	t _{CHDX}	5	-	ns	
Clock Low to Output Valid	t _{CLQV}	0	10	ns	

JTAG TIMING DIAGRAM



119 BGA PACKAGE DIMENSIONS



NOTE :

1. All Dimensions are in Millimeters.
2. Solder Ball to PCB Offset : 0.10 MAX.
3. PCB to Cavity Offset : 0.10 MAX.

119 BGA PACKAGE THERMAL CHARACTERISTICS

Parameter	Symbol	Min	Typ	Max	Unit	Note
Junction to Ambient(at still air)	Theta_JA	-	-	50	°C/W	
Junction to Ambient(at air flow of 100 LFPM)	Theta_JA	-	-	40	°C/W	
Junction to Case	Theta_JC	-	-	8	°C/W	
Junction to Solder Ball	Theta_JB	-	-	10	°C/W	

NOTE : 1. Junction temperature can be calculated by : $T_J = T_A + P_D \times \Theta_{JA}$.